

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I ² C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	34
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-VFQFN Exposed Pad
Supplier Device Package	48-QFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsam3n1ab-mur

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

1.1 Configuration Summary

The SAM3N4/2/1/0/00 differ in memory size, package and features list. Table 1-1 summarizes the configurations of the 9 devices.

 Table 1-1.
 Configuration Summary

Device	Flash	SRAM	Package	Number of PIOs	ADC	Timer	PDC Channels	USART	DAC
SAM3N4A	256 Kbytes	24 Kbytes	LQFP48 QFN48	34	8 channels	6 ⁽¹⁾	8	1	_
SAM3N4B	256 Kbytes	24 Kbytes	LQFP64 QFN64	47	10 channels	6 ⁽²⁾	10	2	1
SAM3N4C	256 Kbytes	24 Kbytes	LQFP100 BGA100	79	16 channels	6	10	2	1
SAM3N2A	128 Kbytes	16 Kbytes	LQFP48 QFN48	34	8 channels	6 ⁽¹⁾	8	1	_
SAM3N2B	128 Kbytes	16 Kbytes	LQFP64 QFN64	47	10 channels	6(⁽²⁾	10	2	1
SAM3N2C	128 Kbytes	16 Kbytes	LQFP100 BGA100	79	16 channels	6	10	2	1
SAM3N1A	64 Kbytes	8 Kbytes	LQFP48 QFN48	34	8 channels	6 ⁽¹⁾	8	1	_
SAM3N1B	64 Kbytes	8 Kbytes	LQFP64 QFN64	47	10 channels	6 ⁽²⁾	10	2	1
SAM3N1C	64 Kbytes	8 Kbytes	LQFP100 BGA100	79	16 channels	6	10	2	1
SAM3N0A	32 Kbytes	8 Kbytes	LQFP48 QFN48	34	8 channels	6 ⁽¹⁾	8	1	_
SAM3N0B	32 Kbytes	8 Kbytes	LQFP64 QFN64	47	10 channels	6 ⁽²⁾	10	2	1
SAM3N0C	32 Kbytes	8 Kbytes	LQFP100 BGA100	79	16 channels	6	10	2	1
SAM3N00A	16 Kbytes	4 KBytes	LQFP48 QFN48	34	8 channels	6 ⁽¹⁾	8	1	_
SAM3N00B	16 Kbytes	4 KBytes	LQFP64 QFN64	47	10 channels	6 ⁽²⁾	10	2	1

Notes: 1. Only two TC channels are accessible through the PIO.

2. Only three TC channels are accessible through the PIO.





2. SAM3N Block Diagram













Figure 2-3. SAM3N 48-pin version Block Diagramz





4. Package and Pinout

SAM3N4/2/1/0/00 series is pin-to-pin compatible with SAM3S products. Furthermore SAM3N4/2/1/0/00 devices have new functionalities referenced in italic inTable 4-1, Table 4-3 and Table 4-4.

4.1 SAM3N4/2/1/0/00C Package and Pinout

4.1.1 100-lead LQFP Package Outline

Figure 4-1. Orientation of the 100-lead LQFP Package



4.1.2 100-ball TFBGA Package Outline

The 100-Ball TFBGA package has a 0.8 mm ball pitch and respects Green Standards. Its dimensions are $9 \times 9 \times 1.1$ mm.

Figure 4-2. Orientation of the 100-ball TFBGA Package



4.3 SAM3N4/2/1/0/00A Package and Pinout



Figure 4-5. Orientation of the 48-pad QFN Package









4.3.1 48-Lead LQFP and QFN Pinout

1	ADVREF		13	VDDIO	25	TDI/PB4	37	TDO/TRACESWO/ PB5
2	GND	Ī	14	PA16/PGMD4	26	PA6/PGMNOE	38	JTAGSEL
3	PB0/AD4	Ī	15	PA15/PGMD3	27	PA5/PGMRDY	39	TMS/SWDIO/PB6
4	PB1/AD5	[16	PA14/PGMD2	28	PA4/PGMNCMD	40	TCK/SWCLK/PB7
5	PB2/AD6	Ī	17	PA13/PGMD1	29	NRST	41	VDDCORE
6	PB3/AD7	Ī	18	VDDCORE	30	TST	42	ERASE/PB12
7	VDDIN	Ī	19	PA12/PGMD0	31	PA3	43	PB10
8	VDDOUT	Ī	20	PA11/PGMM3	32	PA2/PGMEN2	44	PB11
9	PA17/PGMD5/AD0	Ī	21	PA10/PGMM2	33	VDDIO	45	XOUT/PB8
10	PA18/PGMD6/AD1	Ī	22	PA9/PGMM1	34	GND	46	XIN/P/PB9/GMCK
11	PA19/PGMD7/AD2	Ī	23	PA8/XOUT32/PG MM0	35	PA1/PGMEN1	47	VDDIO
12	PA20/AD3		24	PA7/XIN32/PGMN VALID	36	PA0/PGMEN0	48	VDDPLL

Table 4-4. 48-pin SAM3N4/2/1/0/00A Pinout

Note: The bottom pad of the QFN package must be connected to ground.



5.6 Wake-up Sources

The wake-up events allow the device to exit backup mode. When a wake-up event is detected, the Supply Controller performs a sequence which automatically reenables the core power supply and the SRAM power supply, if they are not already enabled.

Figure 5-4. Wake-up Source



5.7 Fast Start-Up

The SAM3N allows the processor to restart in a few microseconds while the processor is in wait mode. A fast start up can occur upon detection of a low level on one of the 19 wake-up inputs (WKUP0 to 15 + SM + RTC + RTT).

The fast restart circuitry, as shown in Figure 5-5, is fully asynchronous and provides a fast startup signal to the Power Management Controller. As soon as the fast start-up signal is asserted, the PMC automatically restarts the embedded 4 MHz fast RC oscillator, switches the master clock on this 4 MHz clock and reenables the processor clock.



Figure 5-5. Fast Start-Up Sources



SAM3N Summary

7. Processor and Architecture

7.1 ARM Cortex-M3 Processor

- Version 2.0
- Thumb-2 (ISA) subset consisting of all base Thumb-2 instructions, 16-bit and 32-bit.
- Harvard processor architecture enabling simultaneous instruction fetch with data load/store.
- Three-stage pipeline.
- Single cycle 32-bit multiply.
- · Hardware divide.
- Thumb and Debug states.
- Handler and Thread modes.
- · Low latency ISR entry and exit.

7.2 APB/AHB Bridge

The SAM3N4/2/1/0/00 product embeds one peripheral bridge:

The peripherals of the bridge are clocked by MCK.

7.3 Matrix Masters

The Bus Matrix of the SAM3N product manages 3 masters, which means that each master can perform an access concurrently with others, to an available slave.

Each master has its own decoder, which is defined specifically for each master. In order to simplify the addressing, all the masters have the same decodings.

Table 7-1.List of Bus Matrix Masters	
--------------------------------------	--

Master 0	Cortex-M3 Instruction/Data
Master 1	Cortex-M3 System
Master 2	Peripheral DMA Controller (PDC)

7.4 Matrix Slaves

The Bus Matrix of the SAM3N product manages 4 slaves. Each slave has its own arbiter, allowing a different arbitration per slave.

Table 7-2. List of Bus Matrix Slaves

Slave 0	Internal SRAM
Slave 1	Internal ROM
Slave 2	Internal Flash
Slave 3	Peripheral Bridge



SAM3N Summary

9. Memories

9.1 Embedded Memories

9.1.1 Internal SRAM

The SAM3N4 product embeds a total of 24-Kbytes high-speed SRAM.

The SAM3N2 product embeds a total of 16-Kbytes high-speed SRAM.

The SAM3N1 product embeds a total of 8-Kbytes high-speed SRAM.

The SRAM is accessible over System Cortex-M3 bus at address 0x2000 0000.

The SRAM is in the bit band region. The bit band alias region is from $0x2200\ 0000$ and 0x23FF FFFF.

RAM size must be configurable by calibration fuses.

9.1.2 Internal ROM

The SAM3N product embeds an Internal ROM, which contains the SAM Boot Assistant (SAM-BA), In Application Programming routines (IAP) and Fast Flash Programming Interface (FFPI).

At any time, the ROM is mapped at address 0x0080 0000.

9.1.3 Embedded Flash

9.1.3.1 Flash Overview

The Flash of the SAM3N4 (256 Kbytes) is organized in one bank of 1024 pages of 256 bytes (Single plane).

The Flash of the SAM3N2 (128 Kbytes) is organized in one bank of 512 pages of 256 bytes (Single Plane).

The Flash of the SAM3N1 (64 Kbytes) is organized in one bank of 256 pages of 256 bytes (Single plane).

The Flash contains a 128-byte write buffer, accessible through a 32-bit interface.

9.1.3.2 Flash Power Supply

The Flash is supplied by VDDCORE.

9.1.3.3 Enhanced Embedded Flash Controller

The Enhanced Embedded Flash Controller (EEFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped on the APB.

The Enhanced Embedded Flash Controller ensures the interface of the Flash block with the 32bit internal bus. Its 128-bit wide memory interface increases performance.

The user can choose between high performance or lower current consumption by selecting either 128-bit or 64-bit access. It also manages the programming, erasing, locking and unlocking sequences of the Flash using a full set of commands.

One of the commands returns the embedded Flash descriptor definition that informs the system about the Flash organization, thus making the software generic.





9.1.3.4 Flash Speed

The user needs to set the number of wait states depending on the frequency used.

For more details, refer to the AC Characteristics sub section in the product Electrical Characteristics Section.

9.1.3.5 Lock Regions

Several lock bits used to protect write and erase operations on lock regions. A lock region is composed of several consecutive pages, and each lock region has its associated lock bit.

Product	Number of lock bits	Lock region size
SAM3N4	16	16 kbytes (64 pages)
SAM3N2	8	16 kbytes (64 pages)
SAM3N1	4	16 kbytes (64 pages)

Table 9-1. Lock bit number

If a locked-region's erase or program command occurs, the command is aborted and the EEFC triggers an interrupt.

The lock bits are software programmable through the EEFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

9.1.3.6 Security Bit Feature

The SAM3N features a security bit, based on a specific General Purpose NVM bit (GPNVM bit 0). When the security is enabled, any access to the Flash, either through the ICE interface or through the Fast Flash Programming Interface, is forbidden. This ensures the confidentiality of the code programmed in the Flash.

This security bit can only be enabled, through the command "Set General Purpose NVM Bit 0" of the EEFC User Interface. Disabling the security bit can only be achieved by asserting the ERASE pin at 1, after a full Flash erase is performed. When the security bit is deactivated, all accesses to the Flash are permitted.

It is important to note that the assertion of the ERASE pin should always be longer than 200 ms.

As the ERASE pin integrates a permanent pull-down, it can be left unconnected during normal operation. However, it is safer to connect it directly to GND for the final application.

9.1.3.7 Calibration Bits

NVM bits are used to calibrate the brownout detector and the voltage regulator. These bits are factory configured and cannot be changed by the user. The ERASE pin has no effect on the calibration bits.

9.1.3.8 Unique Identifier

Each device integrates its own 128-bit unique identifier. These bits are factory configured and cannot be changed by the user. The ERASE pin has no effect on the unique identifier.



10.1 System Controller and Peripherals Mapping

Please refer to Figure 8-1, "SAM3N4/2/1/0/00 Product Mapping" on page 30.

All the peripherals are in the bit band region and are mapped in the bit band alias region.

10.2 Power-on-Reset, Brownout and Supply Monitor

The SAM3N embeds three features to monitor, warn and/or reset the chip:

- Power-on-Reset on VDDIO
- Brownout Detector on VDDCORE
- Supply Monitor on VDDIO

10.2.1 Power-on-Reset

The Power-on-Reset monitors VDDIO. It is always activated and monitors voltage at start up but also during power down. If VDDIO goes below the threshold voltage, the entire chip is reset. For more information, refer to the Electrical Characteristics section of the datasheet.

10.2.2 Brownout Detector on VDDCORE

The Brownout Detector monitors VDDCORE. It is active by default. It can be deactivated by software through the Supply Controller (SUPC_MR). It is especially recommended to disable it during low-power modes such as wait or sleep modes.

If VDDCORE goes below the threshold voltage, the reset of the core is asserted. For more information, refer to the Supply Controller (SUPC) and Electrical Characteristics sections of the datasheet.

10.2.3 Supply Monitor on VDDIO

The Supply Monitor monitors VDDIO. It is inactive by default. It can be activated by software and is fully programmable with 16 steps for the threshold (between 1.9V to 3.4V). It is controlled by the Supply Controller (SUPC). A sample mode is possible. It allows to divide the supply monitor power consumption by a factor of up to 2048. For more information, refer to the SUPC and Electrical Characteristics sections of the datasheet.

10.3 Reset Controller

The Reset Controller is based on a Power-on-Reset cell, and a Supply Monitor on VDDCORE.

The Reset Controller is capable to return to the software the source of the last reset, either a general reset, a wake-up reset, a software reset, a user reset or a watchdog reset.

The Reset Controller controls the internal resets of the system and the NRST pin input/output. It is capable to shape a reset signal for the external devices, simplifying to a minimum connection of a push-button on the NRST pin to implement a manual reset.

The configuration of the Reset Controller is saved as supplied on VDDIO.

10.4 Supply Controller (SUPC)

The Supply Controller controls the power supplies of each section of the processor and the peripherals (via Voltage regulator control)

The Supply Controller has its own reset circuitry and is clocked by the 32 kHz slow clock generator.

3 SAM3N Summary



10.13 Chip Identification

• Chip Identifier (CHIPID) registers permit recognition of the device and its revision.

Table 10-1. SAM3N Chip ID Register		
Chip Name	CHIPID_CIDR	CHIPID_EXID
ATSAM3N4C (Rev A)	0x29540960	0x0
ATSAM3N2C (Rev A)	0x29590760	0x0
ATSAM3N1C (Rev A)	0x29580560	0x0
ATSAM3N4B (Rev A)	0x29440960	0x0
ATSAM3N2B (Rev A)	0x29490760	0x0
ATSAM3N1B (Rev A)	0x29480560	0x0
ATSAM3N4A (Rev A)	0x29340960	0x0
ATSAM3N2A (Rev A)	0x29390760	0x0
ATSAM3N1A (Rev A)	0x29380560	0x0

• JTAG ID: 0x05B2E03F

10.14 UART

- Two-pin UART
 - Implemented features are 100% compatible with the standard Atmel USART
 - Independent receiver and transmitter with a common programmable Baud Rate Generator
 - Even, Odd, Mark or Space Parity Generation
 - Parity, Framing and Overrun Error Detection
 - Automatic Echo, Local Loopback and Remote Loopback Channel Modes
 - Support for two PDC channels with connection to receiver and transmitter

10.15 PIO Controllers

- 3 PIO Controllers, PIOA, PIOB and PIOC (100-pin version only) controlling a maximum of 79 I/O Lines
- · Each PIO Controller controls up to 32 programmable I/O Lines
- Fully programmable through Set/Clear Registers

Table 10-2. PIO available according to pin count

Version	48 pin	64 pin	100 pin
PIOA	21	32	32
PIOB	PIOB 13		15
PIOC	-	-	32

- Multiplexing of four peripheral functions per I/O Line
- For each I/O Line (whether assigned to a peripheral or used as general purpose I/O)
 - Input change, rising edge, falling edge, low level and level interrupt
 - Debouncing and Glitch filter

4 SAM3N Summary



Instance ID	Instance Name	NVIC Interrupt	PMC Clock Control	Instance Description
25	TC2	X	X	Timer/Counter 2
26	TC3	x	X	Timer/Counter 3
27	TC4	X	X	Timer/Counter 4
28	TC5	x	x	Timer/Counter 5
29	ADC	X	X	Analog-to-Digital Converter
30	DACC	X	X	Digital-to-Analog Converter
31	PWM	X	X	Pulse Width Modulation

Table 11-1. Peripheral Identifiers (Continued)

11.2 Peripheral Signals Multiplexing on I/O Lines

The SAM3N product features 2 PIO controllers (48-pin and 64-pin version) or 3 PIO controllers (100-pin version), PIOA, PIOB and PIOC, that multiplex the I/O lines of the peripheral set.

The SAM3N 64-pin and 100-pin PIO Controller controls up to 32 lines (see Table 10-2, "PIO available according to pin count," on page 40). Each line can be assigned to one of three peripheral functions: A, B or C. The multiplexing tables in the following paragraphs define how the I/O lines of the peripherals A, B and C are multiplexed on the PIO Controllers. The column "Comments" has been inserted in this table for the user's own comments; it may be used to track how pins are defined in an application.

Note that some peripheral functions which are output only, might be duplicated within the tables.

SAM3N Summary

11.2.1 PIO Controller A Multiplexing

I/O Line	Peripheral A	Peripheral B	Peripheral C	Extra Function	System Function	Comments
PA0	PWM0	TIOA0		WKUP0		High drive
PA1	PWM1	TIOB0		WKUP1		High drive
PA2	PWM2	SCK0	DATRG	WKUP2		High drive
PA3	TWD0	NPCS3				High drive
PA4	TWCK0	TCLK0		WKUP3		
PA5	RXD0	NPCS3		WKUP4		
PA6	TXD0	PCK0				
PA7	RTS0	PWM3			XIN32	
PA8	CTS0	ADTRG		WKUP5	XOUT32	
PA9	URXD0	NPCS1		WKUP6		
PA10	UTXD0	NPCS2				
PA11	NPCS0	PWM0		WKUP7		
PA12	MISO	PWM1				
PA13	MOSI	PWM2				
PA14	SPCK	PWM3		WKUP8		
PA15		TIOA1		WKUP14		
PA16		TIOB1		WKUP15		
PA17		PCK1		AD0		
PA18		PCK2		AD1		
PA19				AD2/WKUP9		
PA20				AD3/WKUP10		
PA21	RXD1	PCK1		AD8		64/100-pin versions
PA22	TXD1	NPCS3		AD9		64/100-pin versions
PA23	SCK1	PWM0				64/100-pin versions
PA24	RTS1	PWM1				64/100-pin versions
PA25	CTS1	PWM2				64/100-pin versions
PA26		TIOA2				64/100-pin versions
PA27		TIOB2				64/100-pin versions
PA28		TCLK1				64/100-pin versions
PA29		TCLK2				64/100-pin versions
PA30		NPCS2		WKUP11		64/100-pin versions
PA31	NPCS1	PCK2				64/100-pin versions

 Table 11-2.
 Multiplexing on PIO Controller A (PIOA)





12. Embedded Peripherals Overview

12.1 Serial Peripheral Interface (SPI)

- Supports communication with serial external devices
 - Four chip selects with external decoder support allow communication with up to 15 peripherals
 - Serial memories, such as DataFlash and 3-wire EEPROMs
 - Serial peripherals, such as ADCs, DACs, LCD Controllers, CAN Controllers and Sensors
 - External co-processors
- · Master or slave serial peripheral bus interface
 - 8- to 16-bit programmable data length per chip select
 - Programmable phase and polarity per chip select
 - Programmable transfer delays between consecutive transfers and between clock and data per chip select
 - Programmable delay between consecutive transfers
 - Selectable mode fault detection
- · Very fast transfers supported
 - Transfers with baud rates up to MCK
 - The chip select line may be left active to speed up transfers on the same device

12.2 Two Wire Interface (TWI)

- Master, Multi-Master and Slave Mode Operation
- · Compatibility with Atmel two-wire interface, serial memory and I²C compatible devices
- One, two or three bytes for slave address
- · Sequential read/write operations
- Bit Rate: Up to 400 kbit/s
- · General Call Supported in Slave Mode
- Connecting to PDC channel capabilities optimizes data transfers in Master Mode only (for TWI0 only)
 - One channel for the receiver, one channel for the transmitter
 - Next buffer support

12.3 Universal Asynchronous Receiver Transceiver (UART)

- Two-pin UART
 - Implemented features are 100% compatible with the standard Atmel USART
 - Independent receiver and transmitter with a common programmable Baud Rate Generator
 - Even, Odd, Mark or Space Parity Generation
 - Parity, Framing and Overrun Error Detection
 - Automatic Echo, Local Loopback and Remote Loopback Channel Modes

4 SAM3N Summary



- Two multi-purpose input/output signals
- Two global registers that act on all three TC Channels
- Quadrature decoder
 - Advanced line filtering
 - Position/revolution/speed
- 2-bit Gray Up/Down Counter for Stepper Motor

12.6 Pulse Width Modulation Controller (PWM)

- Four channels, one 16-bit counter per channel
- · Common clock generator, providing thirteen different clocks
 - One Modulo n counter providing eleven clocks
 - Two independent linear dividers working on modulo n counter outputs
- Independent channel programming
 - Independent enable/disable commands
 - Independent clock selection
 - Independent period and duty cycle, with double buffering
 - Programmable selection of the output waveform polarity

12.7 10-bit Analog-to-Digital Converter

- Up to 16-channel ADC
- 10-bit 384 Ksamples/sec. or 8-bit 583 Ksamples/sec. Successive Approximation Register ADC
- ±2 LSB Integral Non Linearity, ±1 LSB Differential Non Linearity
- Integrated 8-to-1 multiplexer, offering eight independent 3.3V analog inputs
- · External voltage reference for better accuracy on low voltage inputs
- · Individual enable and disable of each channel
- Multiple trigger source
 - Hardware or software trigger
 - External trigger pin
 - Timer Counter 0 to 2 outputs TIOA0 to TIOA2 trigger
- · Sleep Mode and conversion sequencer
 - Automatic wakeup on trigger and back to sleep mode after conversions of all enabled channels

12.8 Digital-to-Analog Converter (DAC)

- 1 channel 10-bit DAC
- Up to 500 ksamples/s conversion rate
- · Flexible conversion range
- Multiple trigger sources
- One PDC channel







		Millimeter			Inch		
Symbol	Min	Nom	Max	Min	Nom	Max	
A	-	-	1.60	_	_	0.063	
A1	0.05	-	0.15	0.002	_	0.006	
A2	1.35	1.40	1.45	0.053	0.055	0.057	
D		12.00 BSC			0.472 BSC		
D1		10.00 BSC			0.383 BSC		
E		12.00 BSC			0.472 BSC		
E1		10.00 BSC			0.383 BSC		
R2	0.08	-	0.20	0.003	-	0.008	
R1	0.08	-	_	0.003	_	_	
q	0°	3.5°	7°	0°	3.5°	7°	
θ1	0°	-	-	0°	_	-	
θ2	11°	12°	13°	11°	12°	13°	
θ3	11°	12°	13°	11°	12°	13°	
С	0.09	-	0.20	0.004	-	0.008	
L	0.45	0.60	0.75	0.018	0.024	0.030	
L1		1.00 REF		0.039 REF			
S	0.20	-	-	0.008	-	_	
b	0.17	0.20	0.27	0.007	0.008	0.011	
е		0.50 BSC.		0.020 BSC.			
D2		7.50		0.285			
E2		7.50			0.285		
		Tolerance	es of Form an	d Position			
aaa	0.20			0.008			
bbb	0.20			0.008			
CCC		0.08			0.003		
ddd		0.08			0.003		

Table 13-2.	64-lead LQFP Package Dimensions (in mm)

